

Amendments to the Claims

This listing of claims will replace all prior versions, and listings of claims in the application.

1. (currently amended) Method of soldering an item to be soldered in a transit oven with:

heating of the item to be soldered in a preheating zone by means of a preheating device to a temperature which lies below the melting temperature of a solder which is in contact with the item to be soldered,

subjecting the item to be soldered with a first volume flow of a fluid with a first temperature generated by a convection heating means, and

after subjecting the item to be soldered with the first volume flow, subjecting the item to be soldered in a soldering zone with a second volume flow of a fluid with a second temperature which is equal to or different from the first temperature, which is generated by the convection heating means,

~~exposure of the item to be soldered to one or two volume flows of a hot gas with a specified temperature, which lies above the melting temperature of the solder, wherein each of the volume flows applied to the item to be soldered exhibits the specified temperature,~~

~~reduction of the volume flow, wherein the specified temperature is retained or increased, and~~

cooling of the item to be soldered below the melting temperature.

2. (Cancelled)

3. (currently amended) Method according to Claim 2 1, wherein the soldering zone comprises a first section for providing the first volume flow and a second section for providing the second volume flow

4. (currently amended) Method according to Claim 1, wherein at least one of the first and second volume flow is statically reduced.
5. (original) Method according to Claim 3, wherein part of the first volume flow is branched off before entering the soldering zone in order to produce the second volume flow from the remaining proportion of the first volume flow.
6. (original) Method according to Claim 5, wherein the branched off part of the first volume flow is used for preheating a further item to be soldered.
7. (currently amended) Method according to ~~one of the Claims~~ Claim 1 ~~to 6~~, which furthermore comprises: selection of a maximum permissible temperature of the item to be soldered and adjustment of the temperature of the second ~~reduced~~ volume flow to the selected maximum permissible temperature
8. (currently amended) Method according to Claim 7, wherein the second ~~specified~~ temperature is set to the maximum permissible temperature.
9. (currently amended) Method according to Claim 3, wherein at least a first convection heating unit of the ~~convecter heater~~ convection heating means is provided in ~~the~~ a first soldering zone and at least a second convection heating unit of the ~~convecter heater~~ convection heating means is provided in ~~the~~ a second soldering zone.

10. (Cancelled)

11. (currently amended) Method according to ~~one of the Claims~~ Claim 1 to 10, wherein the first volume flow is reduced based on a detection signal obtained from the item to be soldered.

12. -14. (Canceled)

15. (currently amended) Device for soldering an item to be soldered with:

a preheating zone,

a soldering zone which can be exposed to ~~an~~ at least a first and a second adjustable volume flow of hot gas of adjustable temperature by means of a ~~convector heater~~ convection heating means,

a cooling zone, and

a control unit, which is at least functionally connected to the convector heater and is formed so as to cause the first and second volume flow, each one with a specified magnitude and temperature, to act on an item to be soldered in the soldering zone and to cause the second volume flow with lower magnitude ~~and the same or higher or lower~~ temperature to act on the item to be soldered.

16. (currently amended) Device according to Claim 15, whereby the soldering zone comprises at least one first section and one second section in each of which the first and second volume flow can be provided with different magnitude.
17. (currently amended) Device according to Claim 15 ~~or 16~~, wherein at least one preheating zone and at least one cooling zone are provided.
18. (currently amended) Device according to Claim 17, whereby the ~~convective heater~~ heating means comprises a controllable gas guidance system to expose at least the preheating zone and the soldering zone with hot gas at a defined temperature and volume flow in a controlled manner.
19. (currently amended) Device according to Claim 16, wherein the ~~convective heater~~ heating means comprises at least one convection heating element in the first section and at least one convection heating element in the second section.
20. (New) Device according to Claim 16, wherein at least one preheating zone and at least one cooling zone are provided.